

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-9 (Canceled).

Claim 10 (New): A method for manufacturing an electronic part in which a layer having a uniform thickness is formed, the method comprising:  
forming a conductor portion on a surface of a support member;  
bringing an insulating sheet into contact with the conductor portion from above; and  
pressing the insulating sheet to a height of the conductor portion using the conductor portion as a stopper to make the height of the insulating sheet equal to the height of the conductor portion.

Claim 11 (New): A method for manufacturing an electronic part according to claim 10, wherein said conductor portion and said insulating sheet are detached from said surface, after making the height of said insulating sheet equal to the height of said conductor portion.

Claim 12 (New): A method for manufacturing an electronic part according to claim 10, wherein said support member is a substrate of said electronic part.

Claim 13 (New): A method for manufacturing an electronic part according to claim 11, wherein a B-stage sheet is used as said insulating sheet.

Claim 14 (New): A method for manufacturing an electronic part according to claim 12, wherein a B-stage sheet is used as said insulating sheet.

Claim 15 (New): A method for manufacturing an electronic part according to claim 11, wherein a thermoplastic insulating sheet is used as said insulating sheet.

Claim 16 (New): A method for manufacturing an electronic part according to claim 12, wherein a thermoplastic insulating sheet is used as said insulating sheet.

Claim 17 (New): A method for manufacturing an electronic part according to claim 11, wherein heating is performed in addition to said pressing.

Claim 18 (New): A method for manufacturing an electronic part according to claim 12, wherein heating is performed in addition to said pressing.

Claim 19 (New): A method for manufacturing an electronic part according to claim 13, wherein heating is performed in addition to said pressing.

Claim 20 (New): A method for manufacturing an electronic part according to claim 14, wherein heating is performed in addition to said pressing.

Claim 21 (New): A method for manufacturing an electronic part according to claim 15, wherein heating is performed in addition to said pressing.

Claim 22 (New): A method for manufacturing an electronic part according to claim 16, wherein heating is performed in addition to said pressing.

Claim 23 (New): A method for manufacturing an electronic part in which a layer having a uniform thickness is formed, the method comprising:

forming a power supply film on a surface of a support member;  
forming a conductor portion by plating using the power supply film as an electrode;  
bringing an insulating sheet into contact with the conductor portion from above;  
pressing the insulating sheet to the height of the conductor portion using said conductor portion; and  
removing said power supply film.

Claim 24 (New): A method for manufacturing an electronic part according to claim 23, wherein said conductor portion and said insulating sheet are detached from said surface, after making the height of said insulating sheet equal to the height of said conductor portion.

Claim 25 (New): A method of manufacturing an electronic part according to claim 23, wherein said support member is a substrate of said electronic part.

Claim 26 (New): A method for manufacturing an electronic part according to claim 24, wherein a B-stage sheet is used as said insulating sheet.

Claim 27 (New): A method for manufacturing an electronic part according to claim 25, wherein a B-stage sheet is used as said insulating sheet.

Claim 28 (New): A method for manufacturing an electronic part according to claim 24, wherein a thermoplastic insulating sheet is used as said insulating sheet.

Claim 29 (New): A method for manufacturing an electronic part according to claim 25, wherein a thermoplastic insulating sheet is used as said insulating sheet.

Claim 30 (New): A method for manufacturing an electronic part according to claim 24, wherein heating is performed in addition to said pressing.

Claim 31 (New): A method for manufacturing an electronic part according to claim 25, wherein heating is performed in addition to said pressing.

Claim 32 (New): A method for manufacturing an electronic part according to claim 26, wherein heating is performed in addition to said pressing.

Claim 33 (New): A method for manufacturing an electronic part according to claim 27, wherein heating is performed in addition to said pressing.

Claim 34 (New): A method for manufacturing an electronic part according to claim 28, wherein heating is performed in addition to said pressing.

Claim 35 (New): A method for manufacturing an electronic part according to claim 29, wherein heating is performed in addition to said pressing.